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## SN54LS670, SN74LS670 4-BY-4 REGISTER FILES WITH 3-STATE OUTPUTS

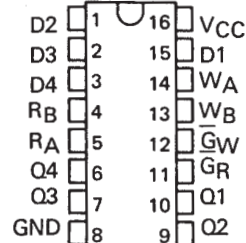
SDLS193 – MARCH 1974 – REVISED MARCH 1988

- **Separate Read/Write Addressing Permits Simultaneous Reading and Writing**
- **Fast Access Times . . . Typically 20 ns**
- **Organized as 4 Words of 4 Bits**
- **Expandable to 512 Words of n-Bits**
- **For Use as:**
  - Scratch-Pad Memory
  - Buffer Storage between Processors
  - Bit Storage in Fast Multiplication Designs
- **3-State Outputs**
- **SN54LS170 and SN74LS170 Are Similar But Have Open-Collector Outputs**

**SN54LS670 . . . J OR W PACKAGE**

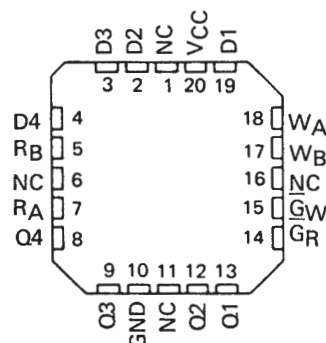
**SN74LS670 . . . D OR N PACKAGE**

(TOP VIEW)



**SN54LS670 . . . FK PACKAGE**

(TOP VIEW)



NC — No internal connection.

### description

The SN54LS670 and SN74LS670 MSI 16-bit TTL register files incorporate the equivalent of 98 gates. The register file is organized as 4 words of 4 bits each and separate on-chip decoding is provided for addressing the four word locations to either write-in or retrieve data. This permits simultaneous writing into one location and reading from another word location.

Four data inputs are available which are used to supply the 4-bit word to be stored. Location of the word is determined by the write-address inputs A and B in conjunction with a write-enable signal. Data applied at the inputs should be in its true form. That is, if a high-level signal is desired from the output, a high-level is applied at the data input for that particular bit location. The latch inputs are arranged so that new data will be accepted only if both internal address gate inputs are high. When this condition exists, data at the D input is transferred to the latch output. When the write-enable input,  $\overline{G_W}$ , is high, the data inputs are inhibited and their levels can cause no change in the information stored in the internal latches. When the read-enable input,  $\overline{G_R}$ , is high, the data outputs are inhibited and go into the high-impedance state.

The individual address lines permit direct acquisition of data stored in any four of the latches. Four individual decoding gates are used to complete the address for reading a word. When the read address is made in conjunction with the read-enable signal, the word appears at the four outputs.

This arrangement—data-entry addressing separate from data-read addressing and individual sense line—eliminates recovery times, permits simultaneous reading and writing, and is limited in speed only by the write time (27 nanoseconds typical) and the read time (24 nanoseconds typical). The register file has a nondestructive readout in that data is not lost when addressed.

All inputs except read enable and write enable are buffered to lower the drive requirements to one Series 54LS/74LS standard load, and input-clamping diodes minimize switching transients to simplify system design. High-speed, double-ended AND-OR-INVERT gates are employed for the read-address function and have high-sink-current, three-state outputs. Up to 128 of these outputs may be bus connected for increasing the capacity up to 512 words. Any number of these registers may be paralleled to provide n-bit word length.

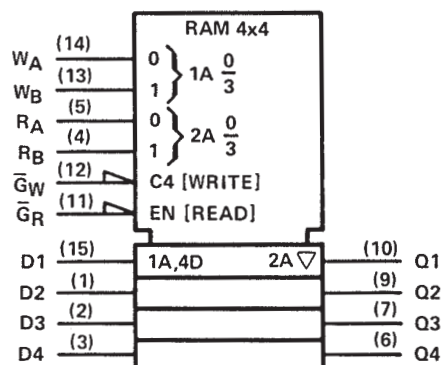
The SN54LS670 is characterized for operation over the full military temperature range of  $-55^{\circ}\text{C}$  to  $125^{\circ}\text{C}$ ; the SN74LS670 is characterized for operation from  $0^{\circ}\text{C}$  to  $70^{\circ}\text{C}$ .

## SN54LS670, SN74LS670

### 4-BY-4 REGISTER FILES WITH 3-STATE OUTPUTS

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logic symbol†



†This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12. Pin numbers shown are for D, J, N, and W packages.

WRITE FUNCTION TABLE (SEE NOTES A, B, AND C)

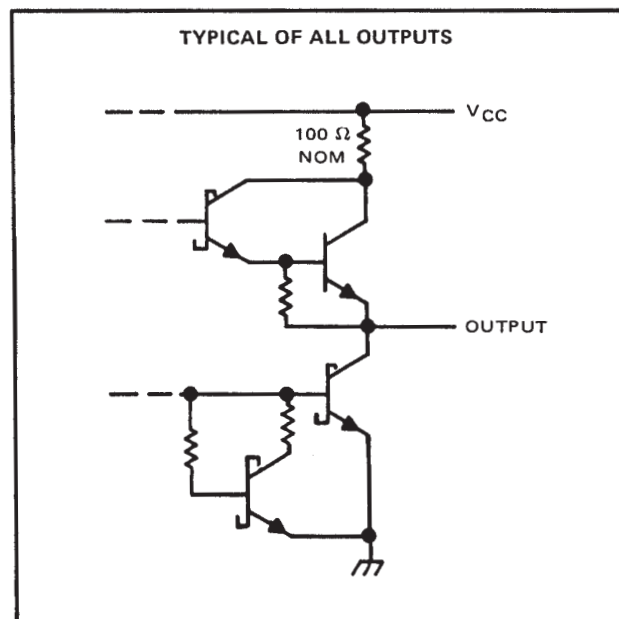
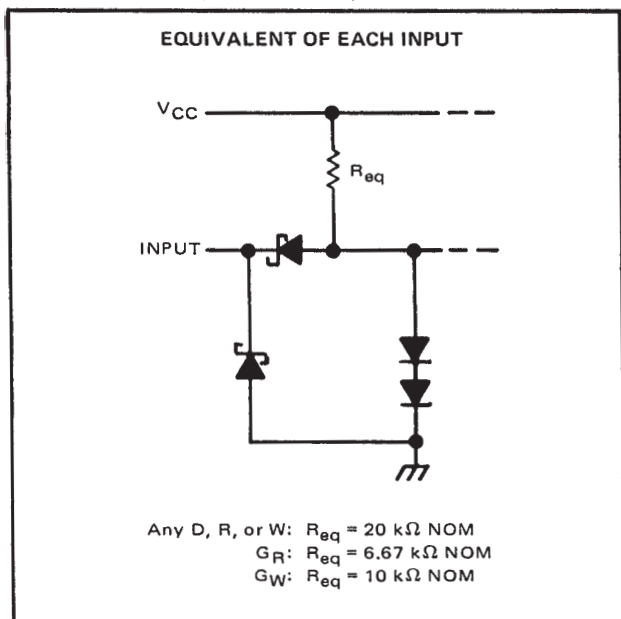
| WRITE INPUTS   |                |             | WORD           |                |                |                |
|----------------|----------------|-------------|----------------|----------------|----------------|----------------|
| W <sub>B</sub> | W <sub>A</sub> | $\bar{G}_W$ | 0              | 1              | 2              | 3              |
| L              | L              | L           | Q = D          | Q <sub>0</sub> | Q <sub>0</sub> | Q <sub>0</sub> |
| L              | H              | L           | Q <sub>0</sub> | Q = D          | Q <sub>0</sub> | Q <sub>0</sub> |
| H              | L              | L           | Q <sub>0</sub> | Q <sub>0</sub> | Q = D          | Q <sub>0</sub> |
| H              | H              | L           | Q <sub>0</sub> | Q <sub>0</sub> | Q <sub>0</sub> | Q = D          |
| X              | X              | H           | Q <sub>0</sub> | Q <sub>0</sub> | Q <sub>0</sub> | Q <sub>0</sub> |

READ FUNCTION TABLE (SEE NOTES A AND D)

| READ INPUTS    |                |             | OUTPUTS |      |      |      |
|----------------|----------------|-------------|---------|------|------|------|
| R <sub>B</sub> | R <sub>A</sub> | $\bar{G}_R$ | Q1      | Q2   | Q3   | Q4   |
| L              | L              | L           | W0B1    | W0B2 | W0B3 | W0B4 |
| L              | H              | L           | W1B1    | W1B2 | W1B3 | W1B4 |
| H              | L              | L           | W2B1    | W2B2 | W2B3 | W2B4 |
| H              | H              | L           | W3B1    | W3B2 | W3B3 | W3B4 |
| X              | X              | H           | Z       | Z    | Z    | Z    |

- NOTES: A. H = high level, L = low level, X = irrelevant, Z = high impedance (off)  
 B. (Q = D) = The four selected internal flip-flop outputs will assume the states applied to the four external data inputs.  
 C. Q<sub>0</sub> = the level of Q before the indicated input conditions were established.  
 D. W0B1 = The first bit of word 0, etc.

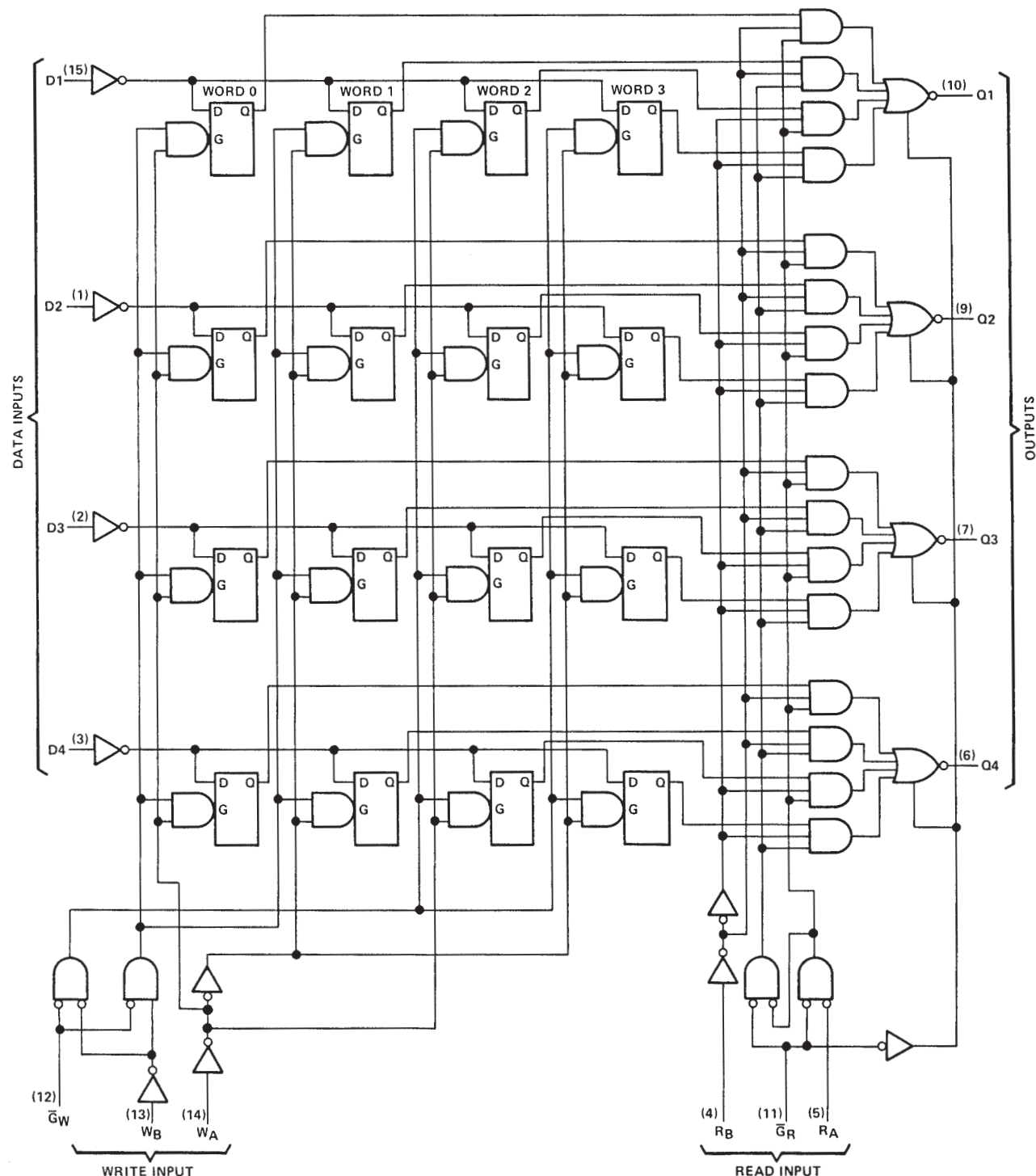
#### schematics of inputs and outputs



# SN54LS670, SN74LS670 4-BY-4 REGISTER FILES WITH 3-STATE OUTPUTS

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logic diagram (positive logic)



Pin numbers shown are for D, J, N, and W packages.

## SN54LS670, SN74LS670 4-BY-4 REGISTER FILES WITH 3-STATE OUTPUTS

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### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

|   |                |
|---|----------------|
| Supply voltage, $V_{CC}$ (see Note 1)           | 7 V            |
| Input voltage                                   | 7 V            |
| Off-state output voltage                        | 5.5 V          |
| Operating free-air temperature range: SN54LS670 | –55°C to 125°C |
| SN74LS670                                       | 0°C to 70°C    |
| Storage temperature range                       | –65°C to 150°C |

### recommended operating conditions

|  |   | SN54LS670 |     |     | SN74LS670 |     |      | UNIT |
|--|---|-----------|-----|-----|-----------|-----|------|------|
|  |   | MIN       | NOM | MAX | MIN       | NOM | MAX  |      |
| Supply voltage, $V_{CC}$   |   | 4.5       | 5   | 5.5 | 4.75      | 5   | 5.25 | V    |
| High-level output current, $I_{OH}$                              |   |           |     | –1  |           |     | –2.6 | mA   |
| Low-level output current, $I_{OL}$                               |   |           |     | 4   |           |     | 8    | mA   |
| Width of write-enable or read-enable pulse, $t_W$                |   | 25        |     |     | 25        |     |      | ns   |
| Setup times, high- or low-level data<br>(see Figure 2)           | Data input with respect to<br>write enable, $t_{su}(D)$   | 10        |     |     | 10        |     |      | ns   |
|  | Write select with respect to<br>write enable, $t_{su}(W)$ | 15        |     |     | 15        |     |      | ns   |
| Hold times, high- or low-level data<br>(see Note 2 and Figure 2) | Data input with respect to<br>write enable, $t_h(D)$      | 15        |     |     | 15        |     |      | ns   |
|  | Write select with respect to<br>write enable, $t_h(W)$    | 5         |     |     | 5         |     |      | ns   |
| Latch time for new data, $t_{latch}$ (see Note 3)                |   | 25        |     |     | 25        |     |      | ns   |
| Operating free-air temperature range, $T_A$                      |   | –55       |     |     | 0         |     |      | °C   |

- NOTES: 1. Voltage values are with respect to network ground terminal.
2. Write-select setup time will protect the data written into the previous address. If protection of data in the previous address is not required,  $t_{su}(W)$  can be ignored as any address selection sustained for the final 30 ns of the write-enable pulse and during  $t_h(W)$  will result in data being written into that location. Depending on the duration of the input conditions, one or a number of previous addresses may have been written into.
3. Latch time is the time allowed for the internal output of the latch to assume the state of new data. See Figure 2. This is important only when attempting to read from a location immediately after that location has received new data.



## SN54LS670, SN74LS670 4-BY-4 REGISTER FILES WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER   | TEST CONDITIONS†  |                           |  | SN54LS670 |      |      | SN74LS670 |      |      | UNIT |    |
|---|---|---------------------------|--|-----------|------|------|-----------|------|------|------|----|
|   |   |                           |  | MIN       | TYP‡ | MAX  | MIN       | TYP‡ | MAX  |      |    |
| V <sub>IH</sub> High-level input voltage                              |   |                           |  | 2         |      |      | 2         |      |      | V    |    |
| V <sub>IL</sub> Low-level input voltage                               |   |                           |  |           |      | 0.7  |           |      | 0.8  | V    |    |
| V <sub>IK</sub> Input clamp voltage                                   | V <sub>CC</sub> = MIN, I <sub>I</sub> = −18 mA                                      |                           |  |           |      | −1.5 |           |      | −1.5 | V    |    |
| V <sub>OH</sub> High-level output voltage                             | V <sub>CC</sub> = MIN, V <sub>IH</sub> = 2 V, V <sub>IL</sub> = V <sub>IL</sub> max | I <sub>OH</sub> = −1 mA   |  | 2.4       | 3.4  |      |           |      |      | V    |    |
|   |   | I <sub>OH</sub> = −2.6 mA |  |           |      |      | 2.4       | 3.1  |      |      |    |
| V <sub>OL</sub> Low-level output voltage                              | V <sub>CC</sub> = MIN, V <sub>IH</sub> = 2 V, V <sub>IL</sub> = V <sub>IL</sub> max | I <sub>OL</sub> = 4 mA    |  | 0.25      | 0.4  |      | 0.25      | 0.4  |      | V    |    |
|   |   | I <sub>OL</sub> = 8 mA    |  |           |      |      | 0.35      | 0.5  |      |      |    |
| I <sub>OZH</sub> Off-state output current, high-level voltage applied | V <sub>CC</sub> = MAX, V <sub>IH</sub> = 2 V, V <sub>O</sub> = 2.7 V                |                           |  | 20        |      |      | 20        |      |      | μA   |    |
| I <sub>OZL</sub> Off-state output current, low-level voltage applied  | V <sub>CC</sub> = MAX, V <sub>IH</sub> = 2 V, V <sub>O</sub> = 0.4 V                |                           |  | −20       |      |      | −20       |      |      | μA   |    |
| I <sub>I</sub> Input current at maximum input voltage                 | V <sub>CC</sub> = MAX, V <sub>I</sub> = 7 V   | Any D, R, or W            |  |           | 0.1  |      |           | 0.1  |      |      | mA |
|   |   | $\overline{G}_W$          |  |           | 0.2  |      |           | 0.2  |      |      |    |
|   |   | $\overline{G}_R$          |  |           | 0.3  |      |           | 0.3  |      |      |    |
| I <sub>IH</sub> High-level input current                              | V <sub>CC</sub> = MAX, V <sub>I</sub> = 2.7 V                                       | Any D, R, or W            |  |           | 20   |      |           | 20   |      |      | μA |
|   |   | $\overline{G}_W$          |  |           | 40   |      |           | 40   |      |      |    |
|   |   | $\overline{G}_R$          |  |           | 60   |      |           | 60   |      |      |    |
| I <sub>IL</sub> Low-level input current                               | V <sub>CC</sub> = MAX, V <sub>I</sub> = 0.4 V                                       | Any D, R, or W            |  |           | −0.4 |      |           | −0.4 |      |      | mA |
|   |   | $\overline{G}_W$          |  |           | −0.8 |      |           | −0.8 |      |      |    |
|   |   | $\overline{G}_R$          |  |           | −1.2 |      |           | −1.2 |      |      |    |
| I <sub>OS</sub> Short-circuit output current§                         | V <sub>CC</sub> = MAX   |                           |  | −30       |      | −130 | −30       |      | −130 | mA   |    |
| I <sub>CC</sub> Supply current  | V <sub>CC</sub> = MAX, See Note 4   |                           |  |           | 30   | 50   |           | 30   | 50   | mA   |    |

†For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡All typical values are at  $V_{CC} = 5 \text{ V}, T_A = 25^\circ\text{C}$ .

§Not more than one output should be shorted at a time, and duration of the short-circuit should not exceed one second.

NOTE 4: Maximum  $I_{CC}$  is guaranteed for the following worst-case conditions: 4.5 V is applied to all data inputs and both enable inputs, all address inputs are grounded and all outputs are open.

switching characteristics,  $V_{CC} = 5 \text{ V}, T_A = 25^\circ\text{C}$

| PARAMETER | FROM<br>(INPUT) | TO<br>(OUTPUT) | TEST CONDITIONS   | MIN | TYP | MAX | UNIT |
|-----------|-----------------|----------------|---|-----|-----|-----|------|
| tPLH      | Read select     | Any Q          | C <sub>L</sub> = 15 pF, R <sub>L</sub> = 2 kΩ,<br>See Figures 1 and 2 | 23  | 40  | ns  |      |
| tPHL      |                 |                |   | 25  | 45  |     |      |
| tPLH      | Write enable    | Any Q          | C <sub>L</sub> = 15 pF, R <sub>L</sub> = 2 kΩ,<br>See Figures 1 and 3 | 26  | 45  | ns  |      |
| tPHL      |                 |                |   | 28  | 50  |     |      |
| tPLH      | Data            | Any Q          |   | 25  | 45  | ns  |      |
| tPHL      |                 |                |   | 23  | 40  |     |      |
| tPZH      | Read enable     | Any Q          | C <sub>L</sub> = 15 pF, R <sub>L</sub> = 2 kΩ,<br>See Figures 1 and 4 | 15  | 35  | ns  |      |
| tPZL      |                 |                |   | 22  | 40  |     |      |
| tPHZ      |                 |                | C <sub>L</sub> = 5 pF, R <sub>L</sub> = 2 kΩ,<br>See Figures 1 and 4  | 30  | 50  | ns  |      |
| tPLZ      |                 |                |   | 16  | 35  |     |      |



**TEXAS  
INSTRUMENTS**

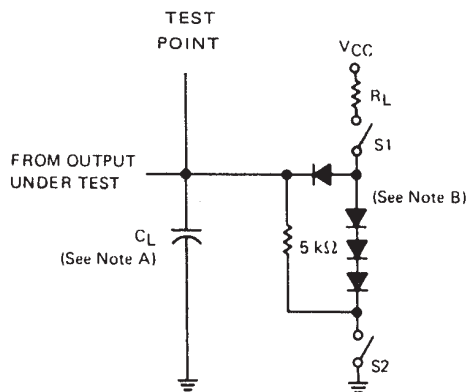
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# SN54LS670, SN74LS670

## 4-BY-4 REGISTER FILES WITH 3-STATE OUTPUTS

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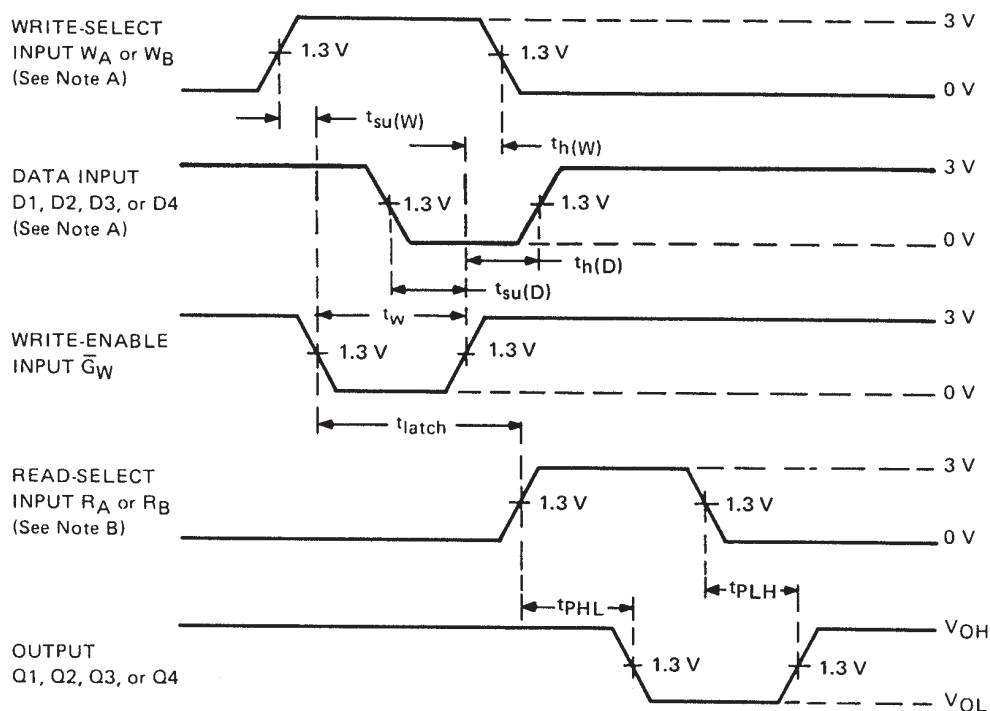
### PARAMETER MEASUREMENT INFORMATION



- NOTES: A.  $C_L$  includes probe and jig capacitance.  
B. All diodes are 1N3064 or equivalent.

LOAD CIRCUIT

FIGURE 1



VOLTAGE WAVEFORMS (S1 AND S2 ARE CLOSED)

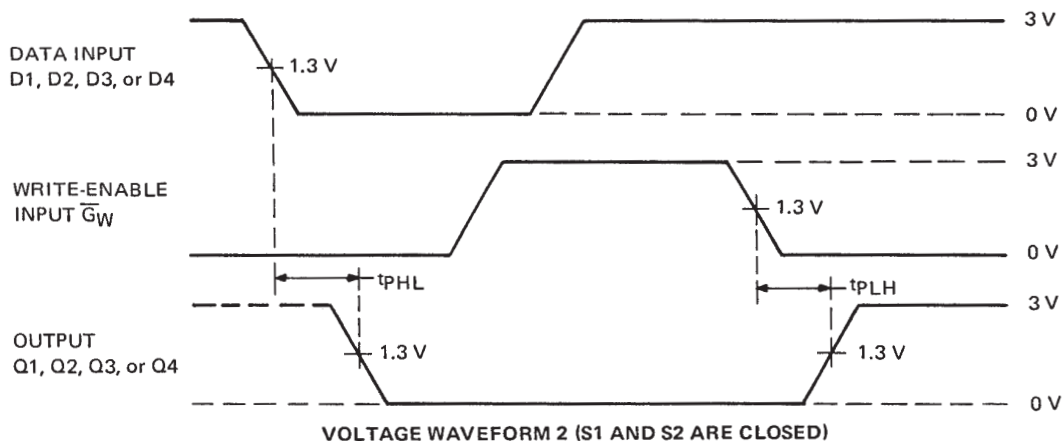
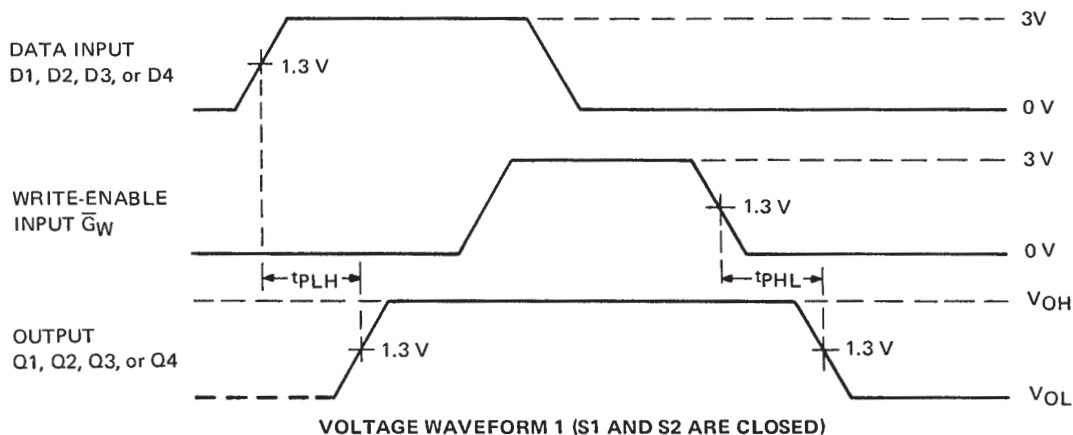
- NOTES: A. High-level input pulses at the select and data inputs are illustrated; however, times associated with low-level pulses are measured from the same reference points.  
B. When measuring delay times from a read-select input, the read-enable input is low.  
C. Input waveforms are supplied by generators having the following characteristics:  $PRR \leq 2 \text{ MHz}$ ,  $Z_{out} \approx 50 \Omega$ , duty cycle  $\leq 50\%$ ,  $t_r \leq 15 \text{ ns}$ ,  $t_f \leq 6 \text{ ns}$ .

FIGURE 2

# SN54LS670, SN74LS670 4-BY-4 REGISTER FILES WITH 3-STATE OUTPUTS

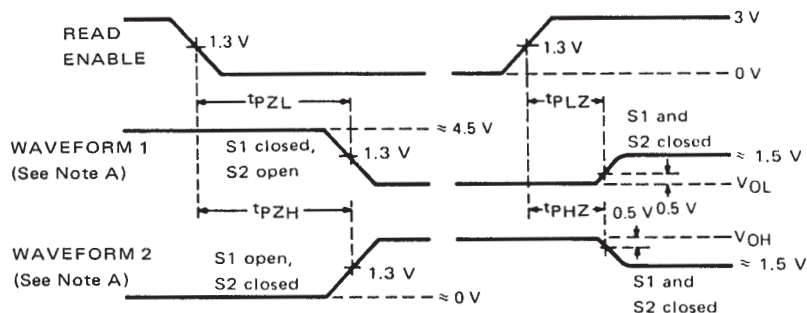
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## PARAMETER MEASUREMENT INFORMATION



- NOTES: A. Each select address is tested. Prior to the start of each of the above tests both write and read address inputs are stabilized with  $W_A = R_A$  and  $W_B = R_B$ . During the test  $G_R$  is low.  
B. Input waveforms are supplied by generators having the following characteristics:  $PRR \leq 1$  MHz,  $Z_{out} \approx 50 \Omega$ , duty cycle  $\leq 50\%$ ,  $t_r \leq 15$  ns,  $t_f \leq 6$  ns.

FIGURE 3



- NOTES: A. Waveforms 1 is for an output with internal conditions such that the output is low except when disabled by the read-enable input. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the read-enable input.  
B. When measuring delay times from the read-enable input, both read-select inputs have been established at steady states.  
C. Input waveforms are supplied by generators having the following characteristics:  $PRR \leq 1$  MHz,  $Z_{out} \approx 50 \Omega$ , duty cycle  $\leq 50\%$ ,  $t_r \leq 15$  ns,  $t_f \leq 6$  ns.

FIGURE 4



**PACKAGING INFORMATION**

| Orderable Device | Status<br>(1) | Package Type | Package<br>Drawing | Pins | Package<br>Qty | Eco Plan<br>(2)            | Lead/Ball Finish<br>(6) | MSL Peak Temp<br>(3) | Op Temp (°C) | Device Marking<br>(4/5)  | Samples                 |
|------------------|---------------|--------------|--------------------|------|----------------|----------------------------|-------------------------|----------------------|--------------|--------------------------|-------------------------|
| 7704201EA        | ACTIVE        | CDIP         | J                  | 16   | 1              | TBD                        | A42                     | N / A for Pkg Type   | -55 to 125   | 7704201EA<br>SNJ54LS670J | <a href="#">Samples</a> |
| 7704201FA        | ACTIVE        | CFP          | W                  | 16   | 1              | TBD                        | A42                     | N / A for Pkg Type   | -55 to 125   | 7704201FA<br>SNJ54LS670W | <a href="#">Samples</a> |
| 7704201FA        | ACTIVE        | CFP          | W                  | 16   | 1              | TBD                        | A42                     | N / A for Pkg Type   | -55 to 125   | 7704201FA<br>SNJ54LS670W | <a href="#">Samples</a> |
| SN54LS670J       | ACTIVE        | CDIP         | J                  | 16   | 1              | TBD                        | A42                     | N / A for Pkg Type   | -55 to 125   | SN54LS670J               | <a href="#">Samples</a> |
| SN54LS670J       | ACTIVE        | CDIP         | J                  | 16   | 1              | TBD                        | A42                     | N / A for Pkg Type   | -55 to 125   | SN54LS670J               | <a href="#">Samples</a> |
| SN74LS670D       | ACTIVE        | SOIC         | D                  | 16   | 40             | Green (RoHS<br>& no Sb/Br) | CU NIPDAU               | Level-1-260C-UNLIM   | 0 to 70      | LS670                    | <a href="#">Samples</a> |
| SN74LS670D       | ACTIVE        | SOIC         | D                  | 16   | 40             | Green (RoHS<br>& no Sb/Br) | CU NIPDAU               | Level-1-260C-UNLIM   | 0 to 70      | LS670                    | <a href="#">Samples</a> |
| SN74LS670N       | ACTIVE        | PDIP         | N                  | 16   | 25             | Pb-Free<br>(RoHS)          | CU NIPDAU               | N / A for Pkg Type   | 0 to 70      | SN74LS670N               | <a href="#">Samples</a> |
| SN74LS670N       | ACTIVE        | PDIP         | N                  | 16   | 25             | Pb-Free<br>(RoHS)          | CU NIPDAU               | N / A for Pkg Type   | 0 to 70      | SN74LS670N               | <a href="#">Samples</a> |
| SN74LS670N3      | OBSOLETE      | PDIP         | N                  | 16   |                | TBD                        | Call TI                 | Call TI              | 0 to 70      |                          |                         |
| SN74LS670N3      | OBSOLETE      | PDIP         | N                  | 16   |                | TBD                        | Call TI                 | Call TI              | 0 to 70      |                          |                         |
| SN74LS670NE4     | ACTIVE        | PDIP         | N                  | 16   | 25             | Pb-Free<br>(RoHS)          | CU NIPDAU               | N / A for Pkg Type   | 0 to 70      | SN74LS670N               | <a href="#">Samples</a> |
| SN74LS670NE4     | ACTIVE        | PDIP         | N                  | 16   | 25             | Pb-Free<br>(RoHS)          | CU NIPDAU               | N / A for Pkg Type   | 0 to 70      | SN74LS670N               | <a href="#">Samples</a> |
| SN74LS670NSR     | ACTIVE        | SO           | NS                 | 16   | 2000           | Green (RoHS<br>& no Sb/Br) | CU NIPDAU               | Level-1-260C-UNLIM   | 0 to 70      | 74LS670                  | <a href="#">Samples</a> |
| SN74LS670NSR     | ACTIVE        | SO           | NS                 | 16   | 2000           | Green (RoHS<br>& no Sb/Br) | CU NIPDAU               | Level-1-260C-UNLIM   | 0 to 70      | 74LS670                  | <a href="#">Samples</a> |
| SNJ54LS670FK     | ACTIVE        | LCCC         | FK                 | 20   | 1              | TBD                        | POST-PLATE              | N / A for Pkg Type   | -55 to 125   | SNJ54LS<br>670FK         | <a href="#">Samples</a> |
| SNJ54LS670FK     | ACTIVE        | LCCC         | FK                 | 20   | 1              | TBD                        | POST-PLATE              | N / A for Pkg Type   | -55 to 125   | SNJ54LS<br>670FK         | <a href="#">Samples</a> |
| SNJ54LS670J      | ACTIVE        | CDIP         | J                  | 16   | 1              | TBD                        | A42                     | N / A for Pkg Type   | -55 to 125   | 7704201EA<br>SNJ54LS670J | <a href="#">Samples</a> |



## Distributor of Texas Instruments: Excellent Integrated System Limited

Datasheet of SN74LS670DR - IC 4X4 REG FILE TRI-ST 16-SOIC

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### PACKAGE OPTION ADDENDUM

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17-Dec-2015

| Orderable Device | Status<br>(1) | Package Type | Package<br>Drawing | Pins | Package<br>Qty | Eco Plan<br>(2) | Lead/Ball Finish<br>(6) | MSL Peak Temp<br>(3) | Op Temp (°C) | Device Marking<br>(4/5)  | Samples                 |
|------------------|---------------|--------------|--------------------|------|----------------|-----------------|-------------------------|----------------------|--------------|--------------------------|-------------------------|
| SNJ54LS670J      | ACTIVE        | CDIP         | J                  | 16   | 1              | TBD             | A42                     | N / A for Pkg Type   | -55 to 125   | 7704201EA<br>SNJ54LS670J | <a href="#">Samples</a> |
| SNJ54LS670W      | ACTIVE        | CFP          | W                  | 16   | 1              | TBD             | A42                     | N / A for Pkg Type   | -55 to 125   | 7704201FA<br>SNJ54LS670W | <a href="#">Samples</a> |
| SNJ54LS670W      | ACTIVE        | CFP          | W                  | 16   | 1              | TBD             | A42                     | N / A for Pkg Type   | -55 to 125   | 7704201FA<br>SNJ54LS670W | <a href="#">Samples</a> |

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSELETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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Datasheet of SN74LS670DR - IC 4X4 REG FILE TRI-ST 16-SOIC

Contact us: [sales@integrated-circuit.com](mailto:sales@integrated-circuit.com) Website: [www.integrated-circuit.com](http://www.integrated-circuit.com)

### PACKAGE OPTION ADDENDUM

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17-Dec-2015

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

#### OTHER QUALIFIED VERSIONS OF SN54LS670, SN54LS670-SP, SN74LS670 :

● Catalog: [SN74LS670](#), [SN54LS670](#)

● Military: [SN54LS670](#)

● Space: [SN54LS670-SP](#)

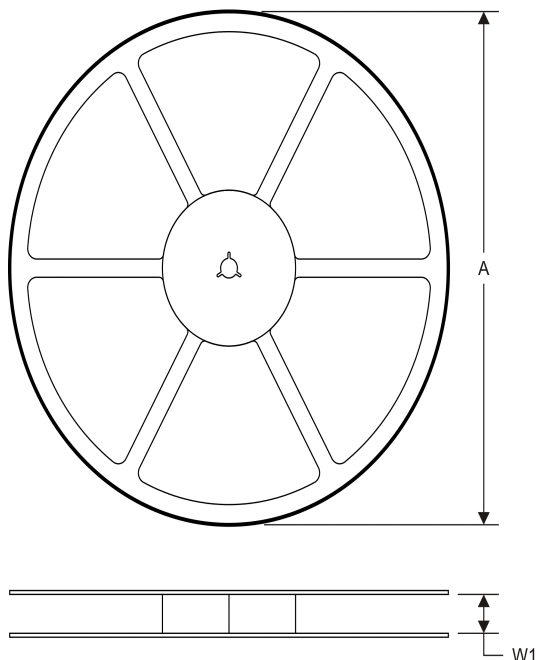
#### NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications
- Space - Radiation tolerant, ceramic packaging and qualified for use in Space-based application

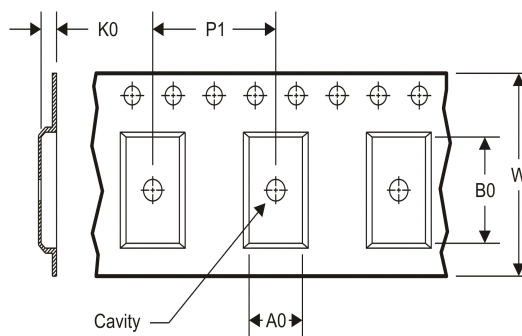
## PACKAGE MATERIALS INFORMATION

### TAPE AND REEL INFORMATION

#### REEL DIMENSIONS



#### TAPE DIMENSIONS



|    |   |
|----|---|
| A0 | Dimension designed to accommodate the component width     |
| B0 | Dimension designed to accommodate the component length    |
| K0 | Dimension designed to accommodate the component thickness |
| W  | Overall width of the carrier tape                         |
| P1 | Pitch between successive cavity centers                   |

#### TAPE AND REEL INFORMATION

\*All dimensions are nominal

| Device       | Package Type | Package Drawing | Pins | SPQ  | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|--------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| SN74LS670NSR | SO           | NS              | 16   | 2000 | 330.0              | 16.4               | 8.2     | 10.5    | 2.5     | 12.0    | 16.0   | Q1            |

**TAPE AND REEL BOX DIMENSIONS**



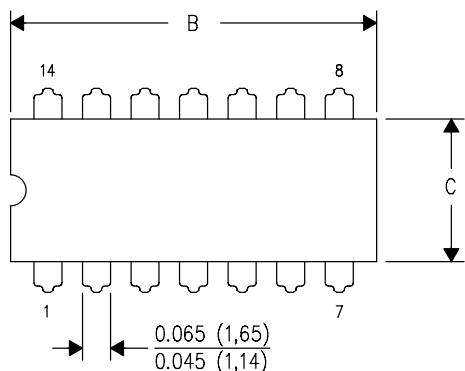
\*All dimensions are nominal

| Device       | Package Type | Package Drawing | Pins | SPQ  | Length (mm) | Width (mm) | Height (mm) |
|--------------|--------------|-----------------|------|------|-------------|------------|-------------|
| SN74LS670NSR | SO           | NS              | 16   | 2000 | 367.0       | 367.0      | 38.0        |

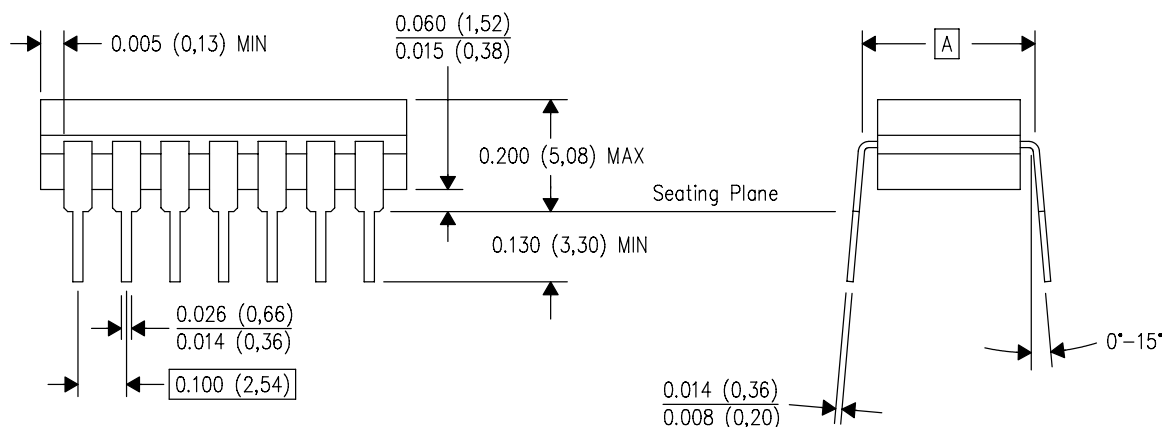
J (R-GDIP-T\*\*)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



| PINS ** | 14                     | 16                     | 18                     | 20                     |
|---------|------------------------|------------------------|------------------------|------------------------|
| DIM     |                        |                        |                        |                        |
| A       | 0.300<br>(7,62)<br>BSC | 0.300<br>(7,62)<br>BSC | 0.300<br>(7,62)<br>BSC | 0.300<br>(7,62)<br>BSC |
| B MAX   | 0.785<br>(19,94)       | .840<br>(21,34)        | 0.960<br>(24,38)       | 1.060<br>(26,92)       |
| B MIN   | —                      | —                      | —                      | —                      |
| C MAX   | 0.300<br>(7,62)        | 0.300<br>(7,62)        | 0.310<br>(7,87)        | 0.300<br>(7,62)        |
| C MIN   | 0.245<br>(6,22)        | 0.245<br>(6,22)        | 0.220<br>(5,59)        | 0.245<br>(6,22)        |



4040083/F 03/03

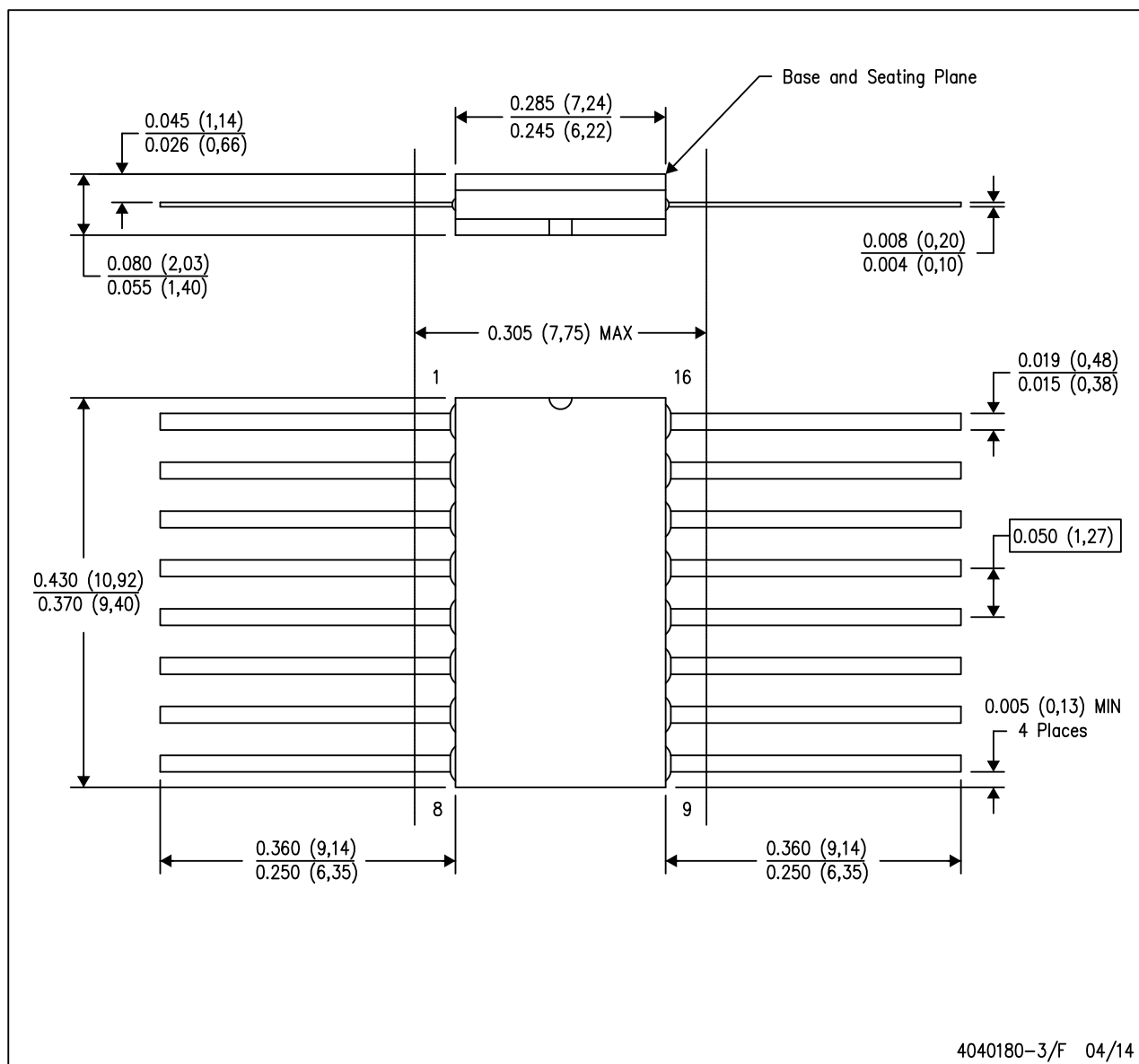
- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package is hermetically sealed with a ceramic lid using glass frit.
  - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.



## MECHANICAL DATA

W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



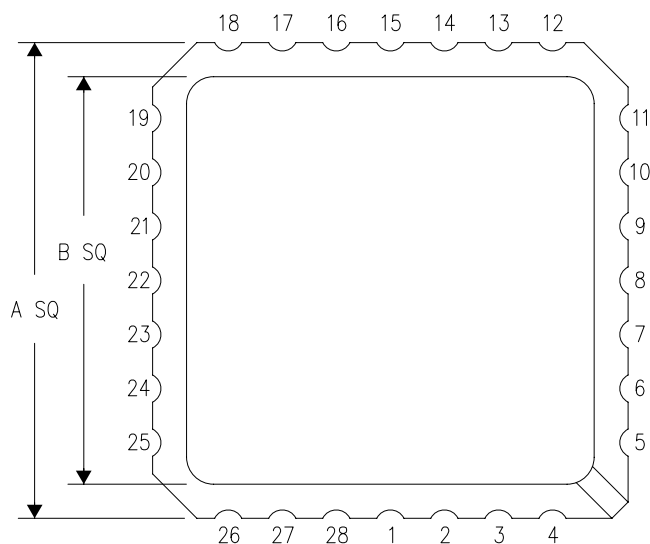
**NOTES:**

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP2-F16

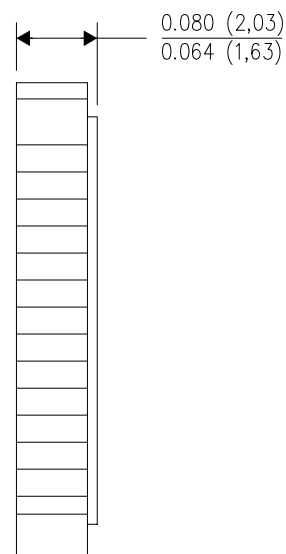
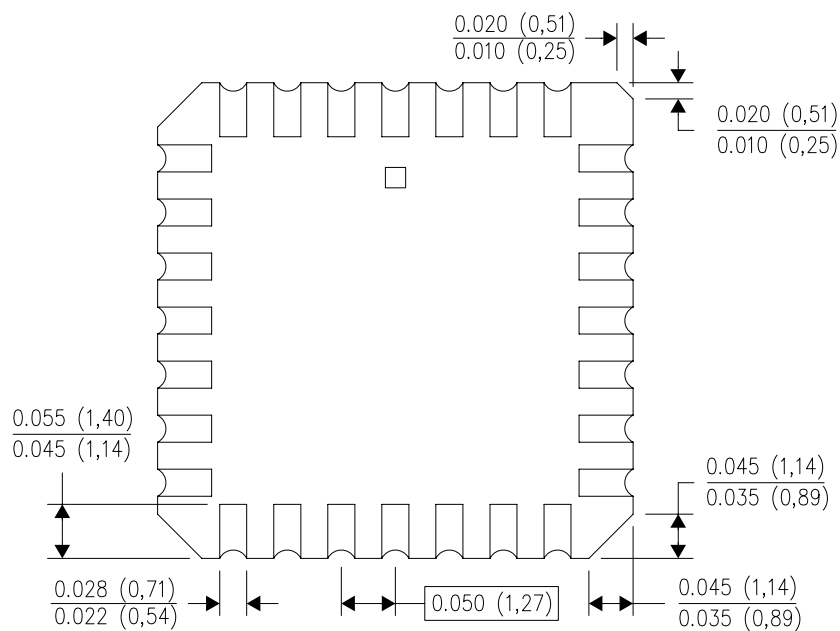
FK (S-CQCC-N\*\*)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



| NO. OF<br>TERMINALS<br>** | A                |                  | B                |                  |
|---------------------------|------------------|------------------|------------------|------------------|
|                           | MIN              | MAX              | MIN              | MAX              |
| 20                        | 0.342<br>(8,69)  | 0.358<br>(9,09)  | 0.307<br>(7,80)  | 0.358<br>(9,09)  |
| 28                        | 0.442<br>(11,23) | 0.458<br>(11,63) | 0.406<br>(10,31) | 0.458<br>(11,63) |
| 44                        | 0.640<br>(16,26) | 0.660<br>(16,76) | 0.495<br>(12,58) | 0.560<br>(14,22) |
| 52                        | 0.740<br>(18,78) | 0.761<br>(19,32) | 0.495<br>(12,58) | 0.560<br>(14,22) |
| 68                        | 0.938<br>(23,83) | 0.962<br>(24,43) | 0.850<br>(21,6)  | 0.858<br>(21,8)  |
| 84                        | 1.141<br>(28,99) | 1.165<br>(29,59) | 1.047<br>(26,6)  | 1.063<br>(27,0)  |



4040140/D 01/11

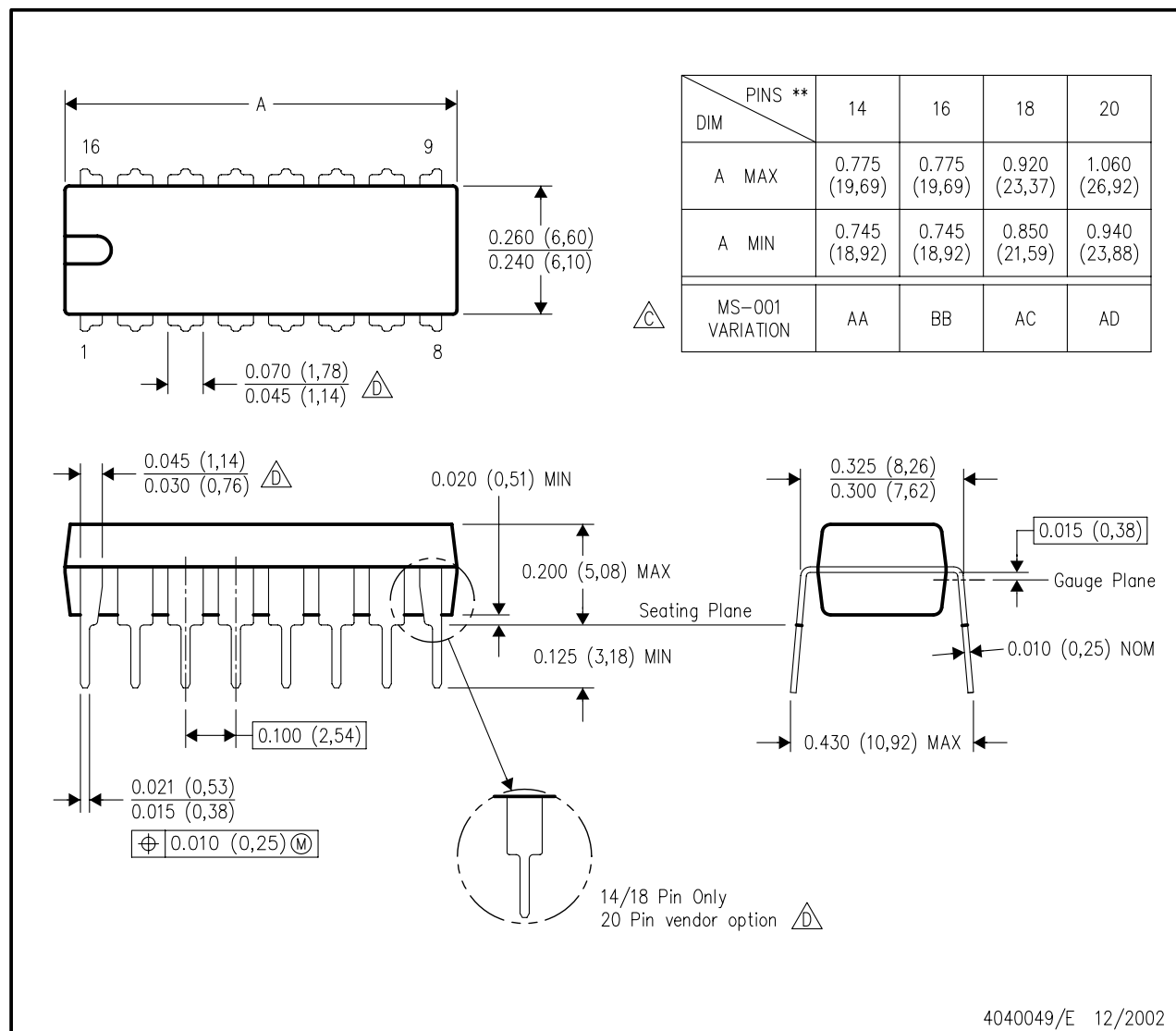
- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package can be hermetically sealed with a metal lid.
  - Falls within JEDEC MS-004

## MECHANICAL DATA

### N (R-PDIP-T\*\*)

16 PINS SHOWN

### PLASTIC DUAL-IN-LINE PACKAGE

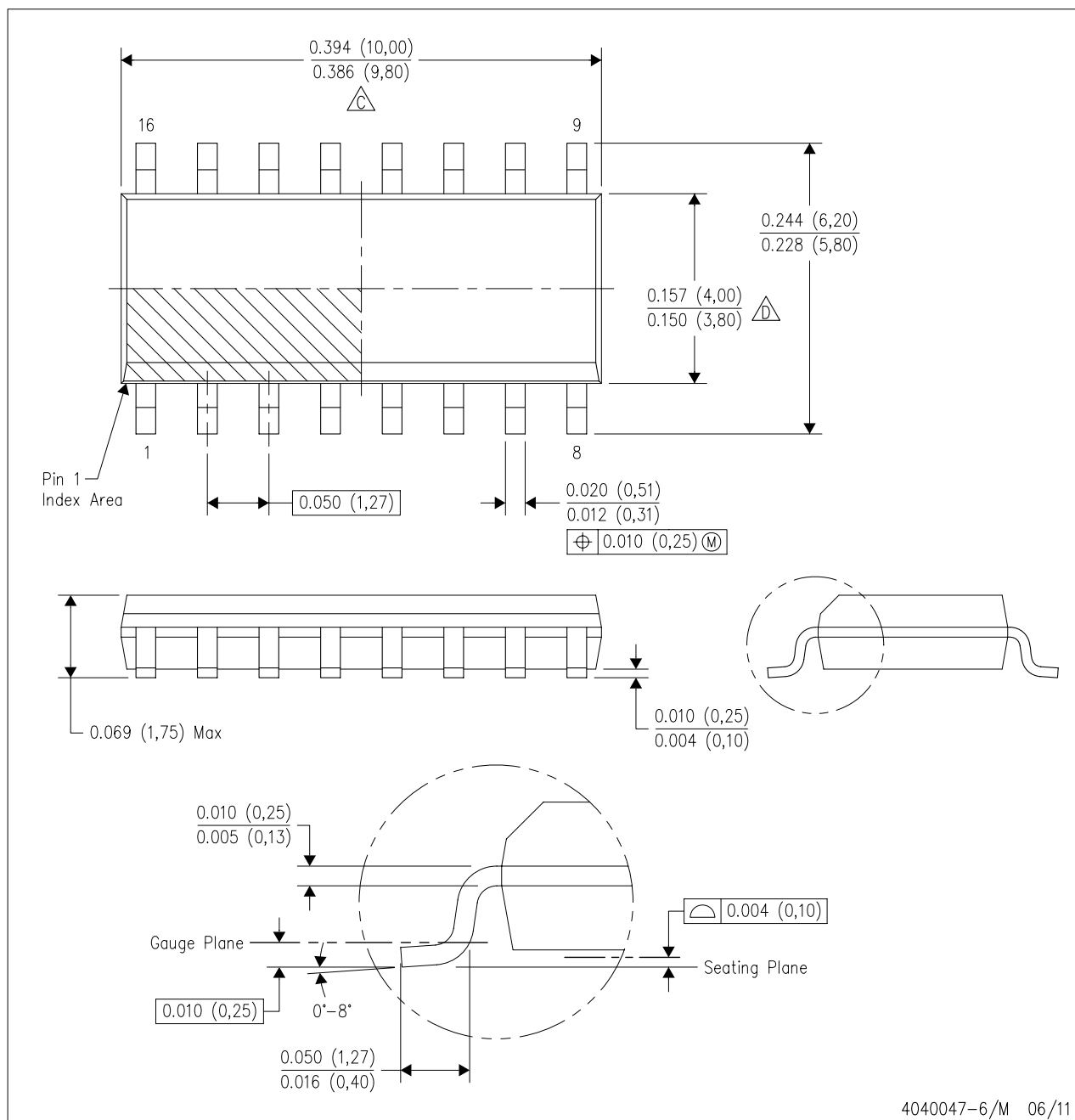


4040049/E 12/2002

## MECHANICAL DATA

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE

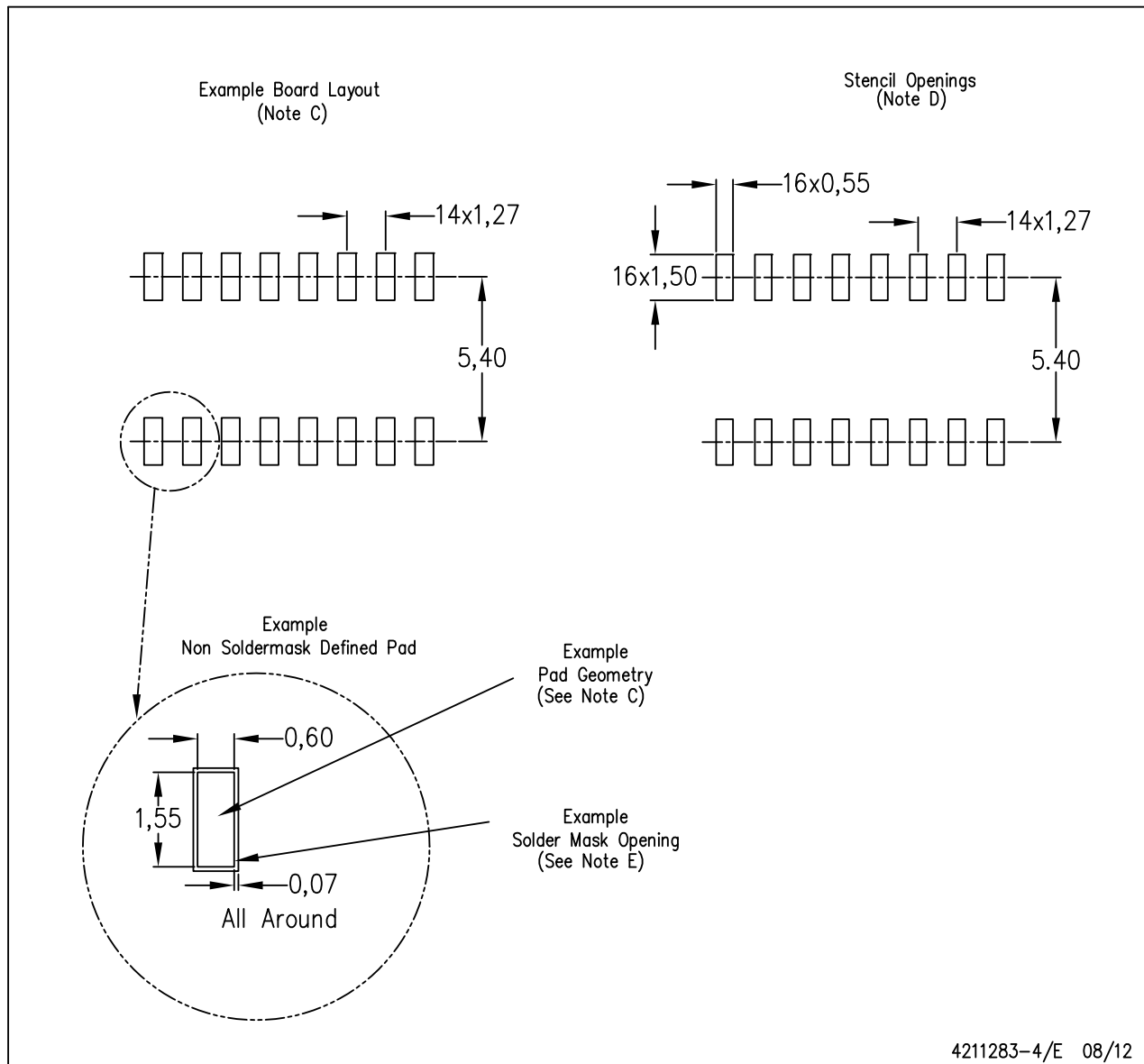


- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
  - Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
  - Reference JEDEC MS-012 variation AC.

## LAND PATTERN DATA

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



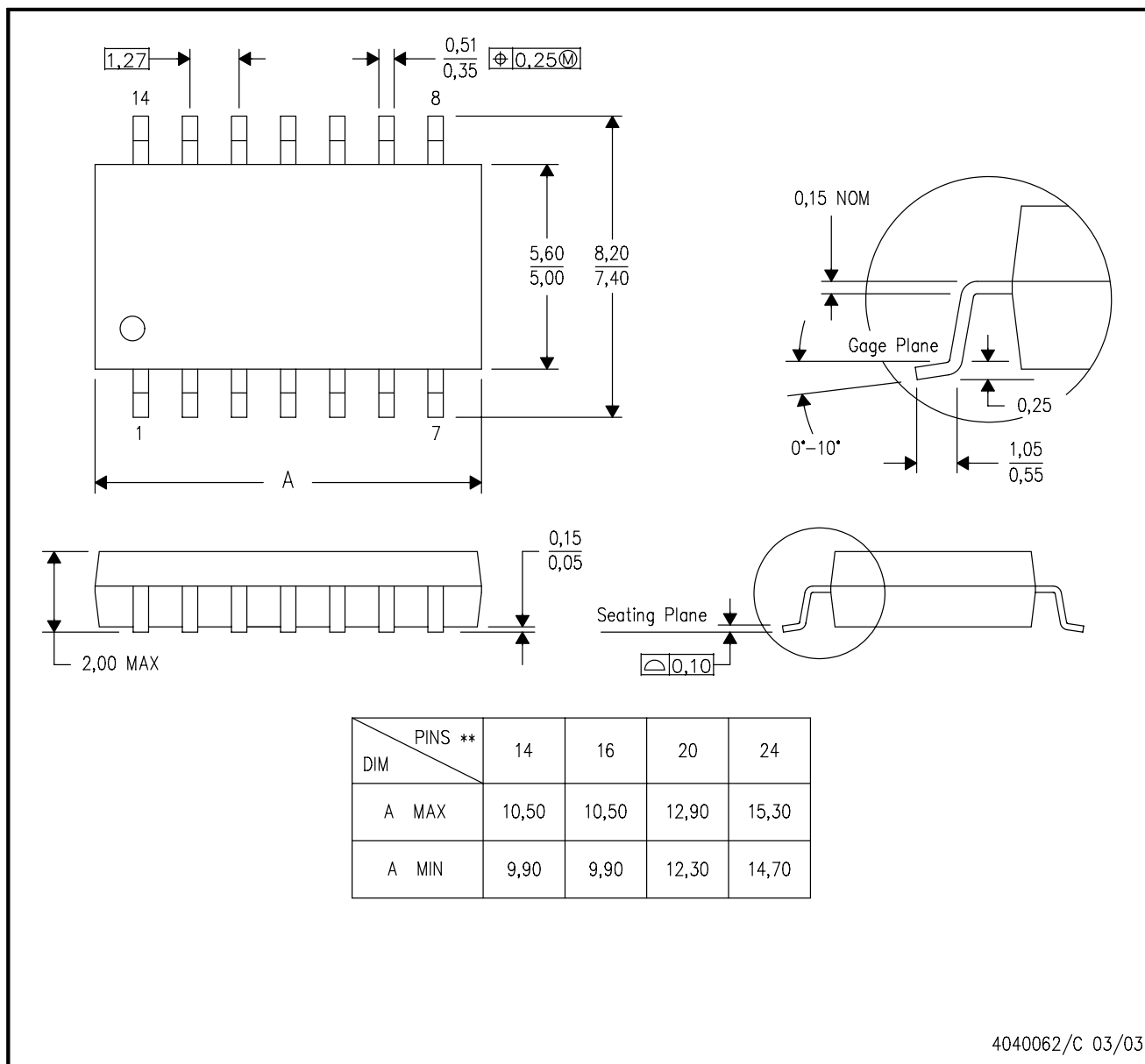
- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Publication IPC-7351 is recommended for alternate designs.
  - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

## MECHANICAL DATA

**NS (R-PDSO-G\*\*)**

**PLASTIC SMALL-OUTLINE PACKAGE**

**14-PINS SHOWN**



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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